PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SRIDHAR GOVINDARAJU	12/20/2013
ANINDYA DASGUPTA	12/20/2013
ROHIT GROVER	12/13/2013

RECEIVING PARTY DATA

Name:	INTEL CORPORATION	
Street Address:	2200 MISSION COLLEGE BOULEVARD	
City:	SANTA CLARA	
State/Country:	CALIFORNIA	
Postal Code:	95054	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14137497

CORRESPONDENCE DATA

Fax Number: (713)468-8883

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

512-418-9944 Phone: Email: tphpto@tphm.com **Correspondent Name:** MARK J. ROZMAN

Address Line 1: 1616 S. VOSS ROAD, SUITE 750 Address Line 2: TROP, PRUNER & HU, P.C.

Address Line 4: HOUSTON, TEXAS 77057

ATTORNEY DOCKET NUMBER: ITL.3113US (P49272) NAME OF SUBMITTER: E.E. "JACK" RICHARDS SIGNATURE: /E.E. "Jack" Richards, II/ **DATE SIGNED:** 07/08/2014

Total Attachments: 4

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PATENT

REEL: 033257 FRAME: 0811 502882136

Attorney Docket No.: ITL.3113US (P49272)

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

GOVINDARAJU, Sridhar; DASGUPTA, Anindya; GROVER, Rohit

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

USING MATERIALS WITH DIFFERENT ETCH RATES TO FILL TRENCHES IN SEMICONDUCTOR DEVICES

(I hereby authorize and request my attorney, associated with Customer Number 47795, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on December 20, 2013 as

United States Application Number 14/137,497 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

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PATENT REEL: 033257 FRAME: 0812 covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

G. Sgridhon GOVINDARAJU, Sridhar	$\frac{ 2 20 201}{(\text{Today's Date})}$	
DASGUPTA, Anindya	(Today's Date)	
GROVER, Rohit	(Today's Date)	

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PATENT REEL: 033257 FRAME: 0813

Attorney Docket No.: ITL.3113US (P49272)

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

GOVINDARAJU, Sridhar

GROVER, Rohit

(Today's Date)

Dec, 20th, 2013 (Today's Date)

(Today's Date)

Attorney Docket No.: ITL.3113US (P49272)

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

GOVINDARAJU, Sridhar

(Today's Date)

DASGUPTA, Anindya

(Today's Date)

GROVER, Rohit

(Today's Date)

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